



STS4C3F30L

N-channel 30V - 0.044Ω - 5A - SO-8
STripFET™ Power MOSFET

General features

Type	V _{DSS}	R _{DS(on)}	I _D
STS4C3F30L (n-ch)	30V	<0.055Ω	5A
STS4C3F30L (p-ch)	30V	<0.165Ω	3A

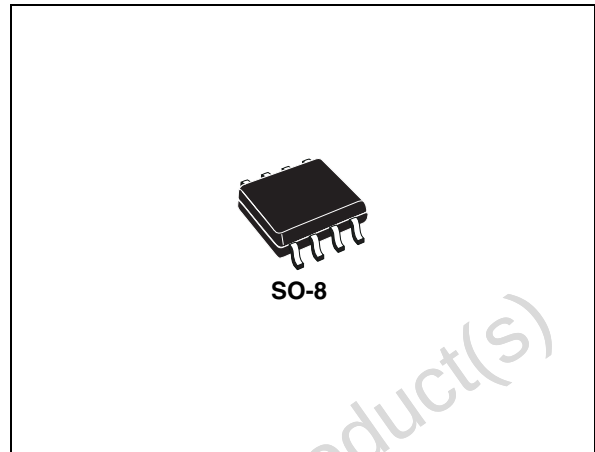
- Low threshold drive
- Standard outline for easy automated surface mount assembly

Description

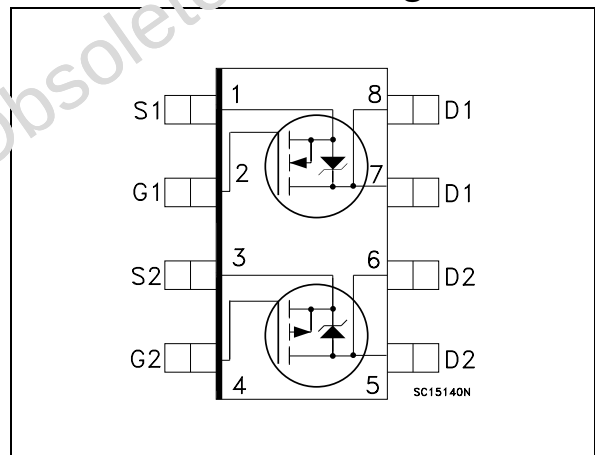
This application specific MOSFET is the second generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

- Switching application



Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STS4C3F30L	S4C3F30L	SO-8	Tape & reel

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Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		N-channel	P-channel	
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	30		V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20\text{ k}\Omega$)	30		V
V_{GS}	Gate- source voltage	± 16		V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$ S.O.	5	2.7	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$ S.O.	3.2	1.7	A
$I_{DM}^{(1)}$	Drain current (pulsed)	20	11	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$ D.O.	1.6		W
	Total dissipation at $T_C = 25^\circ\text{C}$ S.O.	2		W
T_{stg}	Storage temperature	-60 to 150		W/ $^\circ\text{C}$
T_j	Max. operating junction temperature	150		$^\circ\text{C}$

1. Pulse width limited by safe operating area

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case S.O.	62.5	$^\circ\text{C}/\text{W}$
	Thermal resistance junction-case D.O.	78.0	$^\circ\text{C}/\text{W}$
T_l	Maximum lead temperature for soldering purpose	300	$^\circ\text{C}$

2 Electrical characteristics

($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0$	n-ch p-ch	30 30			V V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating, @ } 125^{\circ}\text{C}$	n-ch p-ch			1 1	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{V}$	n-ch p-ch			± 100 ± 100	nA nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	n-ch p-ch	1 1	1.6 1.6	2.5 2.5	V V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{V}$, $I_D = 2\text{A}$ $V_{GS} = 10\text{V}$, $I_D = 1.5\text{A}$ $V_{GS} = 4.5\text{V}$, $I_D = 2\text{A}$ $V_{GS} = 4.5\text{V}$, $I_D = 1.5\text{A}$	n-ch p-ch n-ch p-ch		0.044 0.145 0.051 0.160	0.055 0.165 0.065 0.20	Ω Ω Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$, $I_D = 3.5\text{A}$ $V_{DS} > I_{D(on)} \times R_{DS(on)max}$, $I_D = 2\text{A}$	n-ch p-ch		6 4		S S
C_{iss}	Input capacitance		n-ch p-ch		220 420		pF pF
C_{oss}	Output capacitance	$V_{DS} = 25\text{V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	n-ch p-ch		115 95		pF pF
C_{rss}	Reverse transfer capacitance		n-ch p-ch		23 30		pF pF
Q_g	Total gate charge	N-channel $V_{DD} = 24\text{V}$, $I_D = 5\text{ A}$ $V_{GS} = 10\text{V}$	n-ch p-ch		9.5 4.8	2 7	nC nC
Q_{gs}	Gate-source charge	P-channel $V_{DD} = 15\text{V}$, $I_D = 3\text{ A}$ $V_{GS} = 4.5\text{V}$	n-ch p-ch		2.25 1.7		nC nC
Q_{gd}	Gate-drain charge	(see Figure 24)	n-ch p-ch		1.7 2		nC nC

1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

Table 5. Switching times

Symbol	Parameter	Test conditions		Min.	Typ.	Max	Unit
$t_{d(on)}$	Turn-on delay time	N-channel $V_{DD} = 15V, I_D = 2.5 A$ $R_G = 4.7\Omega, V_{GS} = 10V$ P-channel $V_{DD} = 15V, I_D = 1.5 A$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ (see Figure 26)	n-ch		13		ns
			p-ch		15		ns
t_r	Rise time		n-ch		27		ns
			p-ch		37		ns
$t_{d(off)}$	Turn-off-delay time		n-ch		10		ns
			p-ch		90		ns
t_f	Fall time		n-ch		3		ns
			p-ch		23		ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions		Min	Typ.	Max	Unit
I_{SD}	Source-drain current		n-ch			5	A
			p-ch			3	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		n-ch			20	A
			p-ch			12	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 4 A, V_{GS} = 0$	n-ch			1.2	V
			p-ch			1.2	V
t_{rr}	Reverse recovery time	N-channel $I_{SD} = 3.5A, di/dt=100A/\mu s$ $V_{DD} = 15V, T_J = 150^\circ C$ P-channel $I_{SD} = 3A, di/dt=100 A/\mu s$ $V_{DD} = 15V, T_J = 150^\circ C$ (see Figure 28)	n-ch		28		ns
			p-ch		35		ns
Q_{rr}	Reverse recovery charge		n-ch		18		nC
			p-ch		25		nC
I_{RRM}	Reverse recovery current		n-ch		1.3		A
			p-ch		1.5		A

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area n-ch

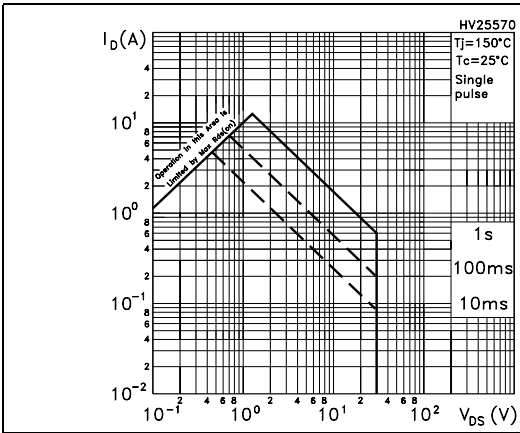


Figure 2. Thermal impedance n-ch

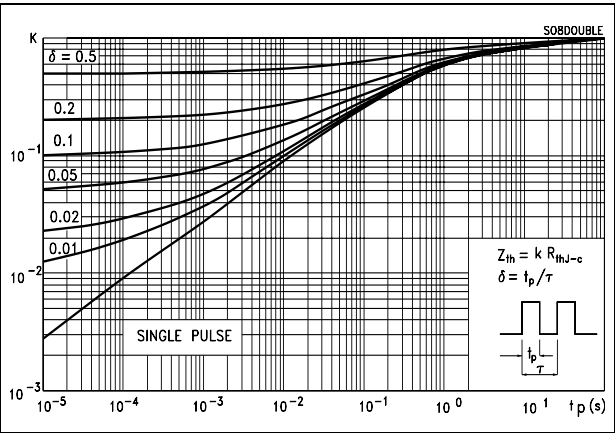


Figure 3. Output characteristics n-ch

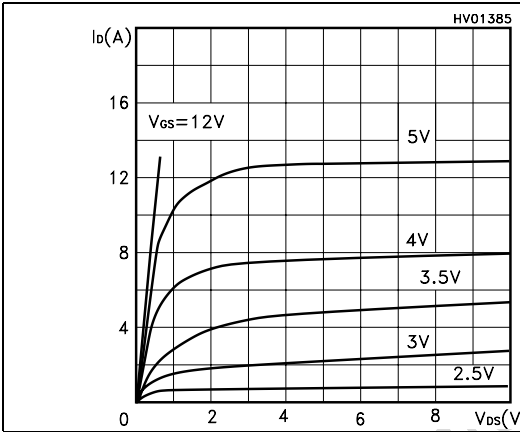


Figure 4. Transfer characteristics n-ch

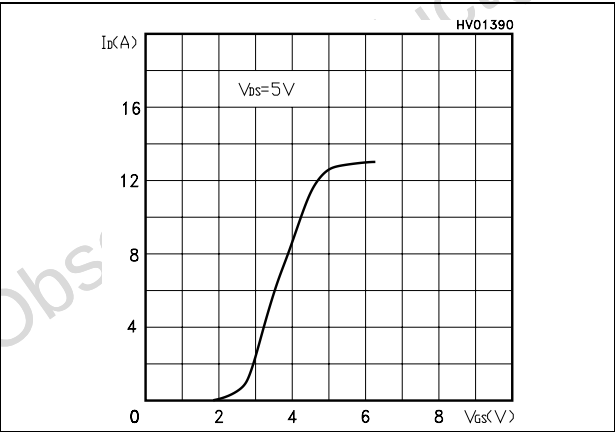


Figure 5. Transconductance n-ch

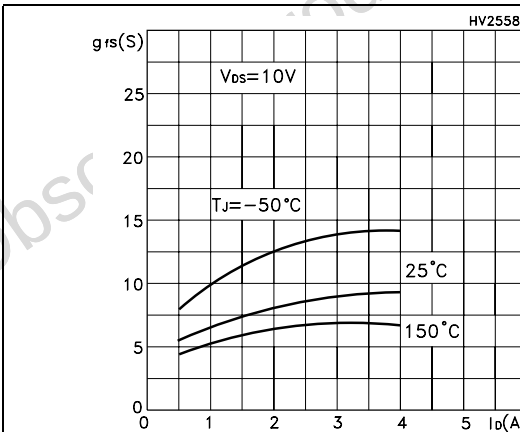


Figure 6. Static drain-source on resistance n-ch

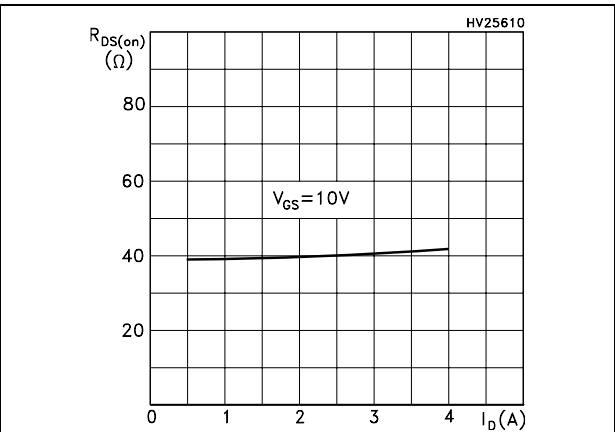


Figure 7. Gate charge vs gate-source voltage n-ch

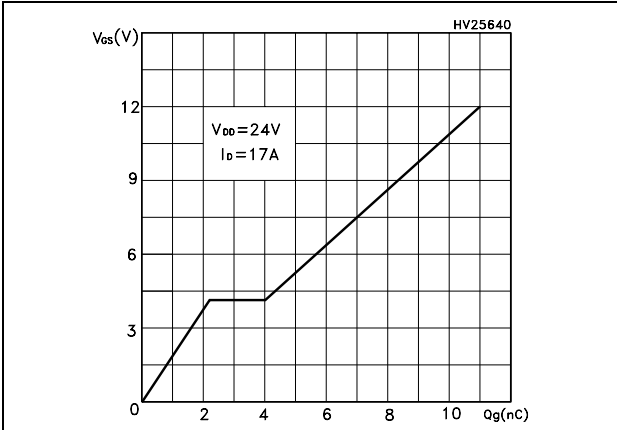


Figure 8. Capacitance variations n-ch

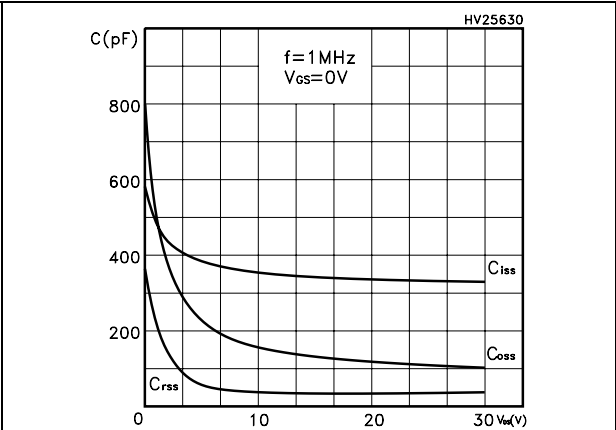


Figure 9. Normalized gate threshold voltage vs temperature n-ch

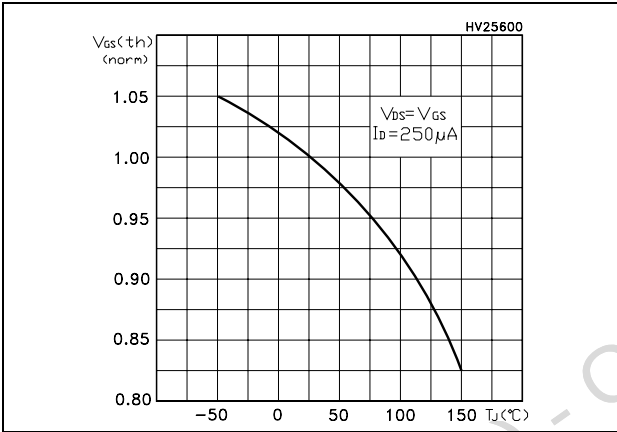


Figure 10. Normalized on resistance vs temperature n-ch

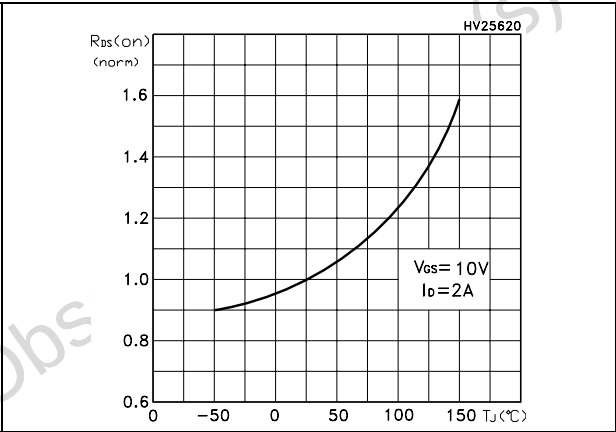


Figure 11. Source-drain diode forward characteristics n-ch

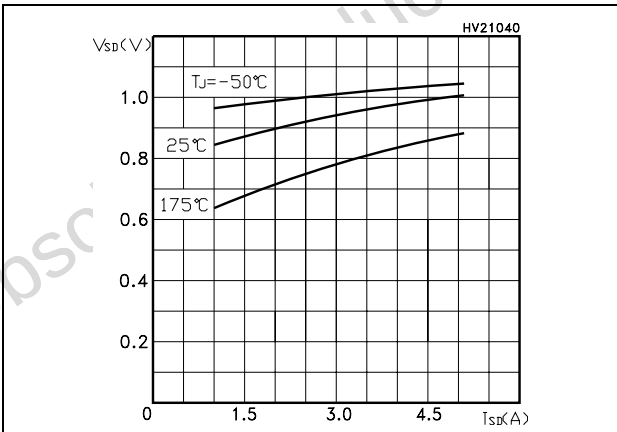


Figure 12. Safe operating area p-ch

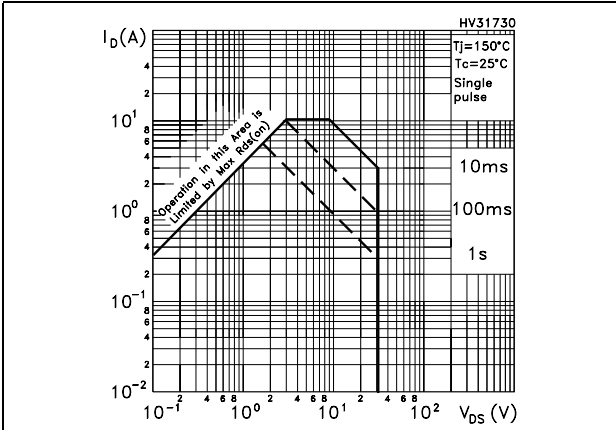


Figure 13. Thermal impedance p-ch

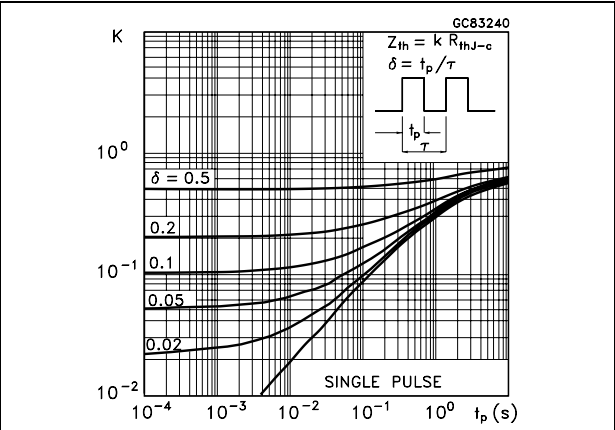


Figure 14. Output characteristics p-ch

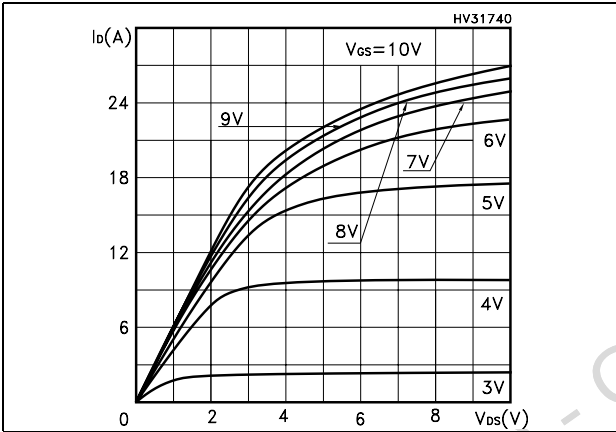


Figure 15. Transfer characteristics p-ch

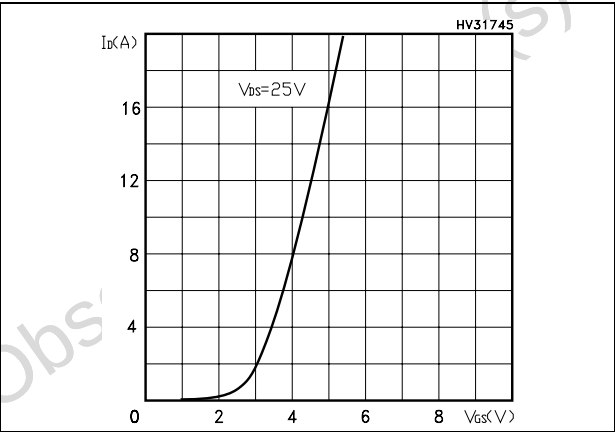


Figure 16. Transconductance p-ch

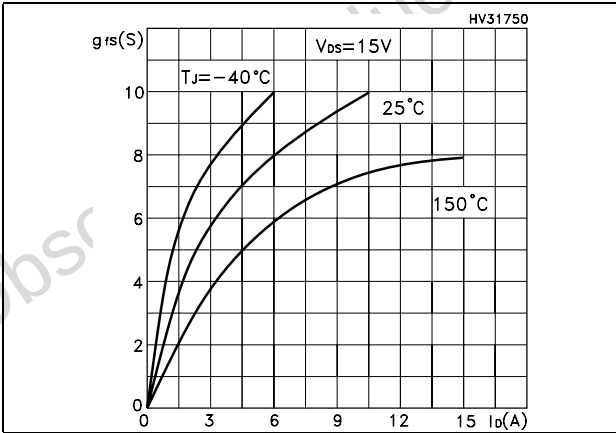


Figure 17. Static drain-source on resistance p-ch

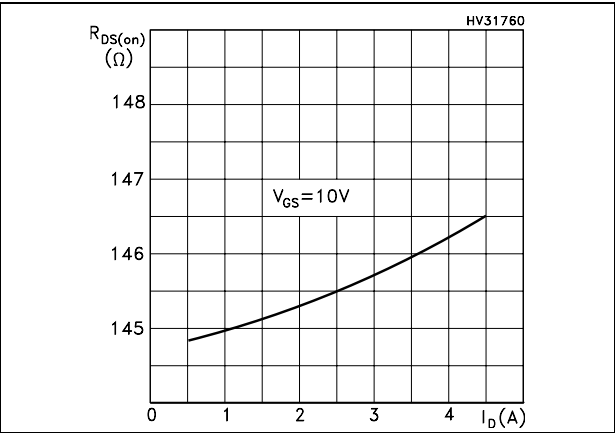


Figure 18. Gate charge vs gate-source voltage p-ch

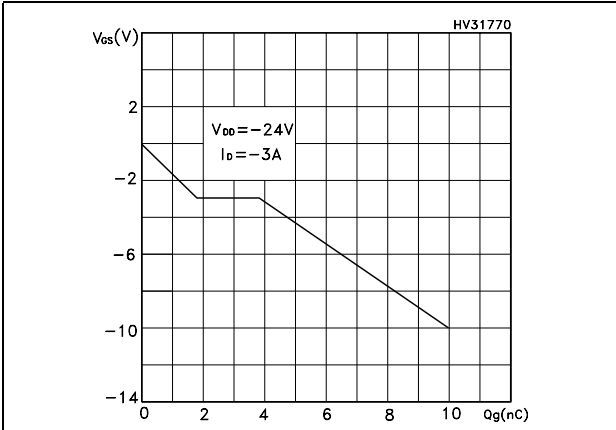


Figure 19. Capacitance variations p-ch

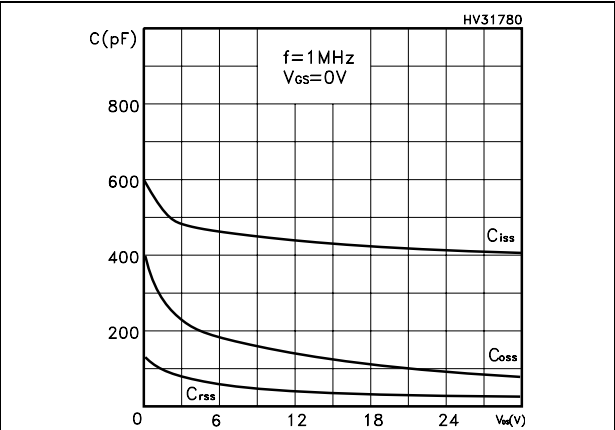


Figure 20. Normalized gate threshold voltage vs temperature p-ch

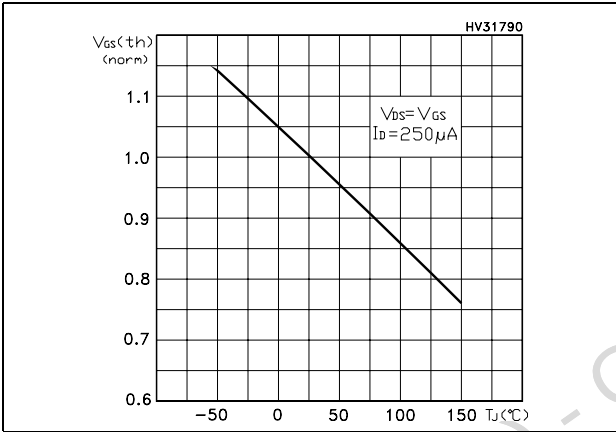


Figure 21. Normalized on resistance vs temperature p-ch

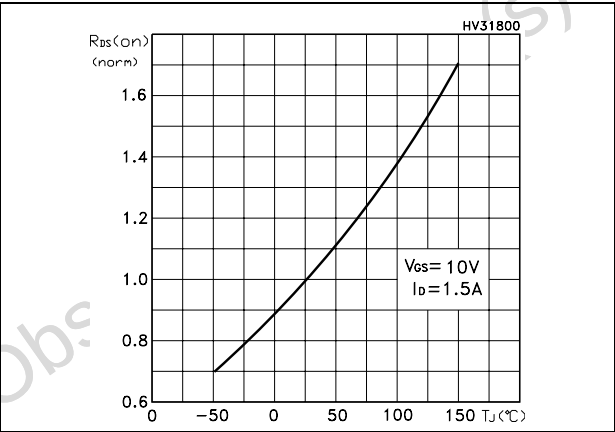
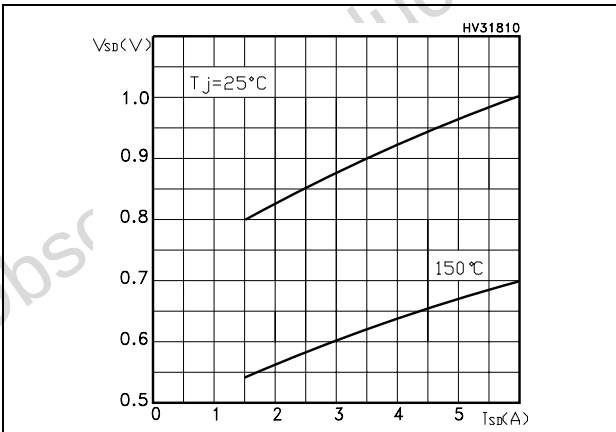


Figure 22. Source-drain diode forward characteristics p-ch



3 Test circuit

Figure 23. Switching times test circuit for resistive load

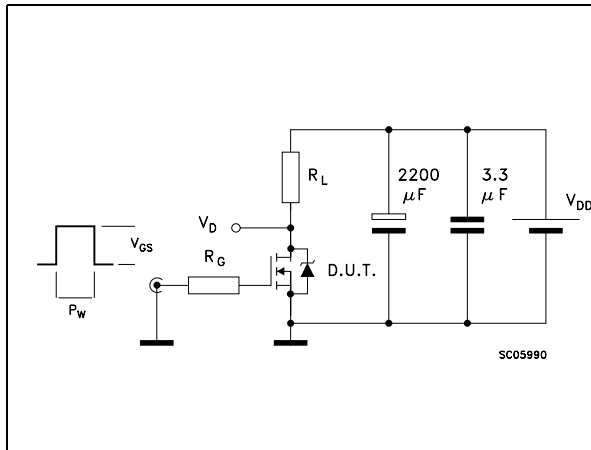


Figure 24. Gate charge test circuit

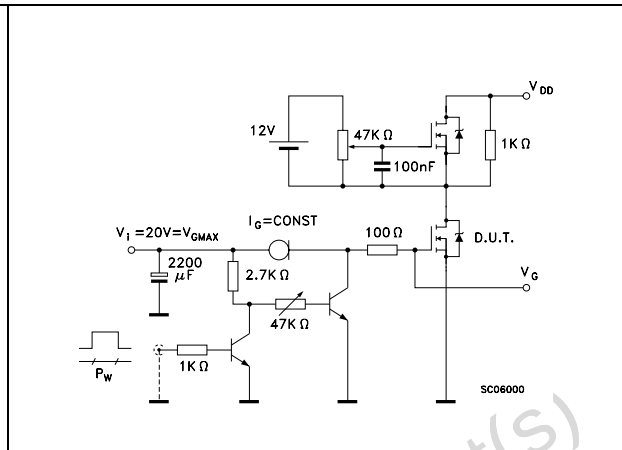


Figure 25. Test circuit for inductive load switching and diode recovery times

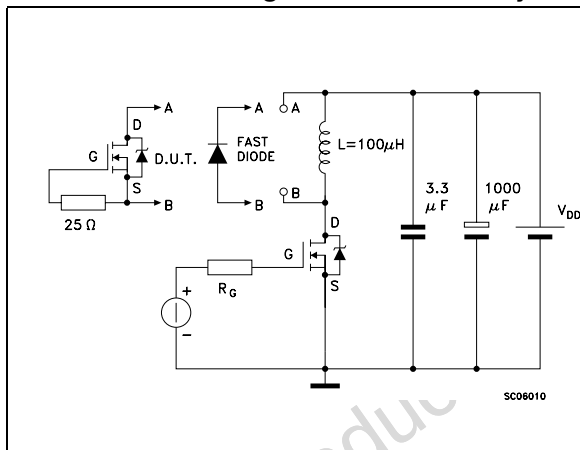


Figure 26. Unclamped Inductive load test circuit

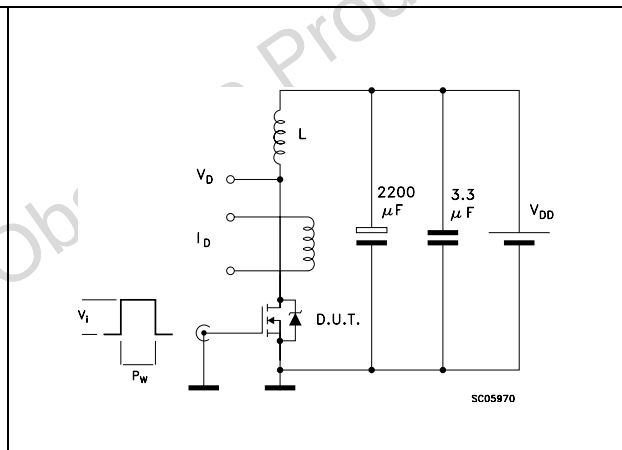


Figure 27. Unclamped inductive waveform

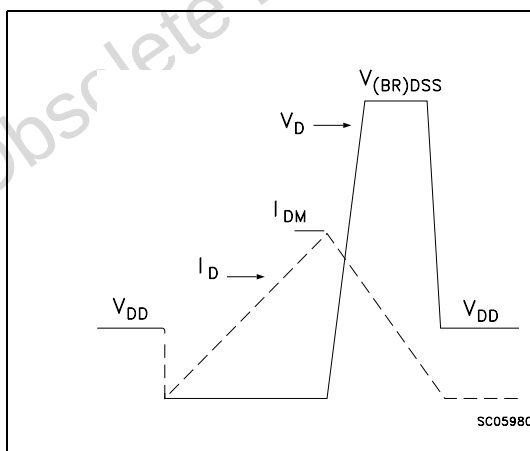
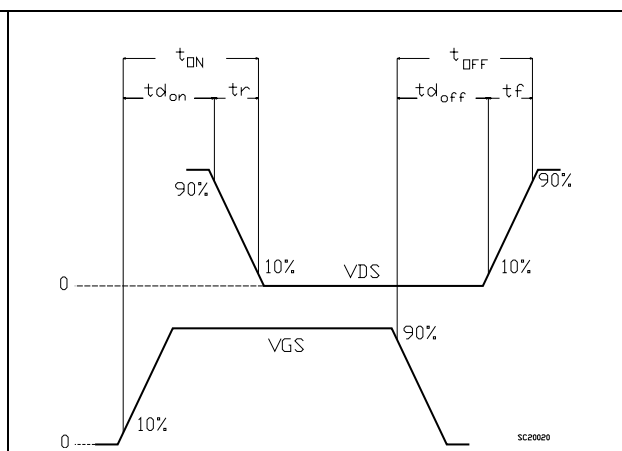


Figure 28. Switching time waveform

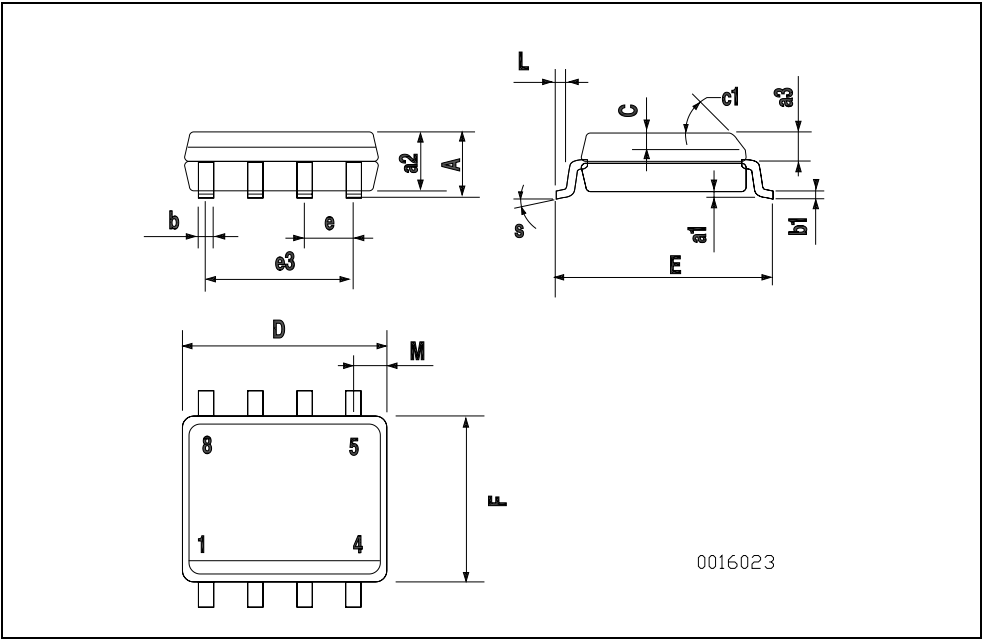


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Obsolete Product(s) - Obsolete Product(s)

SO-8 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1	45 (typ.)					
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S	8 (max.)					



5 Revision history

Table 7. Revision history

Date	Revision	Changes
12-May-2006	1	First release

Obsolete Product(s) - Obsolete Product(s)

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